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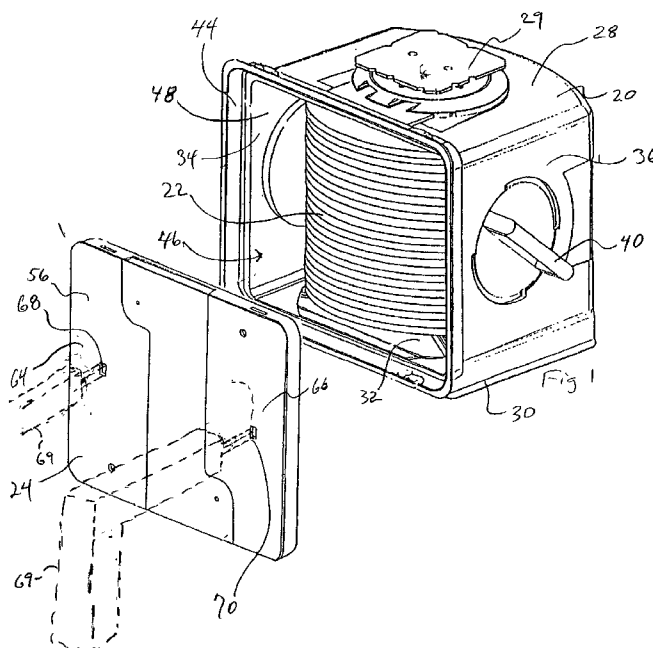
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(54) Title: FRONT OPENING WAFER CARRIER WITH PATH TO GROUND EFFECTUATED BY DOOR



(57) Abstract: A front opening wafer carrier formed principally of plastic and comprising an enclosure portion (20) and a door (24) has a path to ground with respect to the wafers (22), the path to ground effectuated by the door (24). The base "ground" may be provided at the machine interface upon which the carrier sits, or through the robotic arm that grasps, operates and moves the door (24).



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